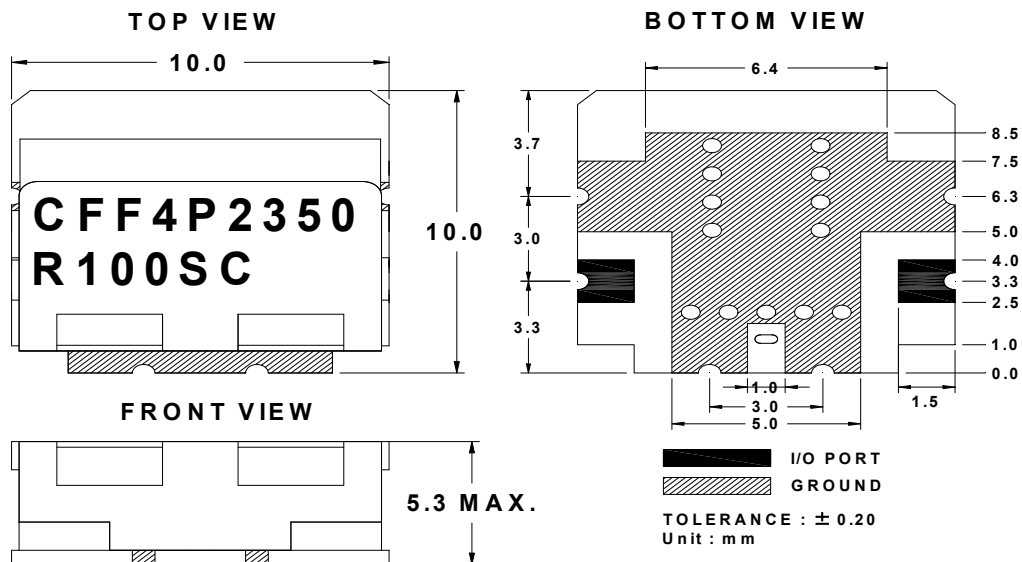


Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	2350.0	MHz
Bandwidth [BW]	fo ±50.0 [2300.0~2400.0]	MHz
Insertion Loss in BW	3.0	dB max
Ripple in BW	1.0	dB max
Return Loss in BW	15.0	dB min
Attenuation ☐ Absolute Value ☒ Relative Value	30dBc min. @ fo ± [1.0 ~ 2176.0]	MHz
	15dBc min. @ fo ± [2176.0 ~ 2263.0]	MHz
	2.0 dBc min. @ fo ± [2263.0 ~ 2280.0]	MHz
	2 dBc min. @ fo ± [2420 ~]	MHz
	20.0 dBc min. @ fo ± [4200.0 ~ 4720.0]	MHz
	TBD dBc min. @ fo ± [4720.0 ~ 6000.0]	MHz
Group Delay Variation		ns max
Input Power	1.0	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

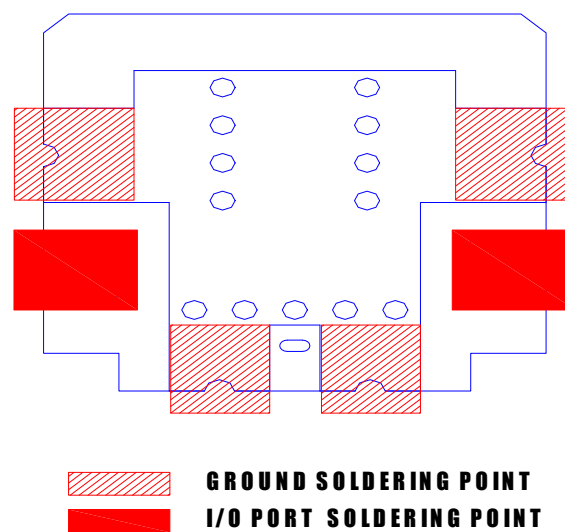
Mechanical Specification



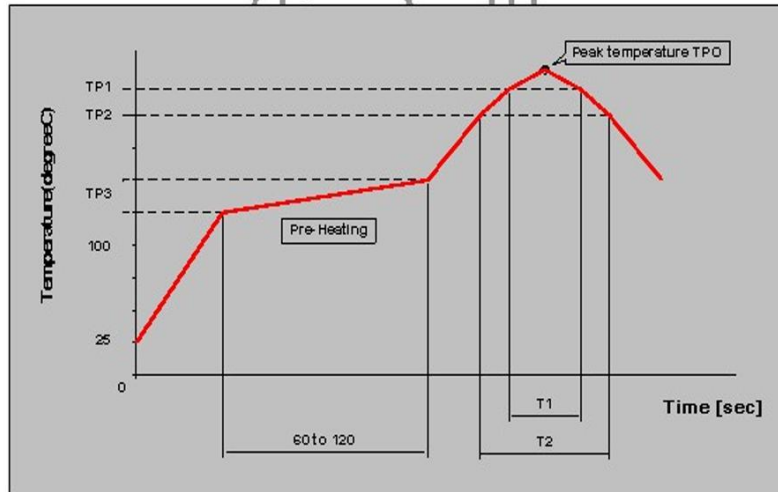
Plot Data



Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180